- Package Options Include Plastic "Small Outline" Packages, Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

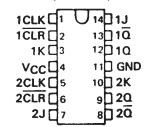
description

The '73, and 'H73, contain two independent J-K flip-flops with individual J-K, clock, and direct clear inputs. The '73, and 'H73, are positive pulse-triggered flip-flops. J-K input is loaded into the master while the clock is high and transferred to the slave on the high-to-low transition. For these devices the J and K inputs must be stable while the clock is high.

The 'LS73A contains two independent negative-edge-triggered flip-flops. The J and K inputs must be stable one setup time prior to the high-to-low clock transition for predictable operation. When the clear is low, it overrides the clock and data inputs forcing the Ω output low and the $\overline{\Omega}$ output high.

The SN5473, SN54H73, and the SN54LS73A are characterized for operation over the full military temperature range of -55 °C to 125 °C. The SN7473, and the SN74LS73A are characterized for operation from 0 °C to 70 °C.

SN5473, SN54LS73A . . . J OR W PACKAGE SN7473 . . . N PACKAGE SN74LS73A . . . D OR N PACKAGE (TOP VIEW)



73
FUNCTION TABLE

| | INPUT | S | | OUTE | PUTS |
|-----|-------|---|---|------|--------------------|
| CLR | CLK | J | K | Q | ā |
| L | × | Х | Х | L | Н |
| Н | Ţ | L | L | QO | \overline{a}^{O} |
| Н | 九 | Н | L | H | L |
| Н | ъ. | L | Н | L | Н |
| Н | л | Н | Н | TOG | GLE |

'L\$73A FUNCTION TABLE

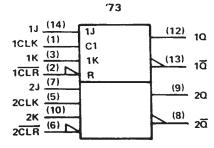
| | INPUT | OUTP | UTS | | |
|-----|-------|------|-----|-----|--------------------|
| CLR | CLK | J | K | Q | ₫ |
| L | X | Х | Х | L | Н |
| н | 1 | L | L | αo | \overline{a}_{0} |
| н | 1 | Н | L | Н | L |
| н | 1 | L | н | L | н |
| н | 4 | Н | Н | TOG | GLE |
| н | Н | Х | Х | αo | \bar{a}_0 |

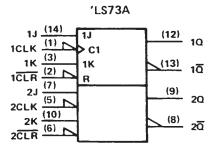
FOR CHIP CARRIER INFORMATION.
CONTACT THE FACTORY



SDLS118 - DECEMBER 1983 - REVISED MARCH 1988

logic symbols†



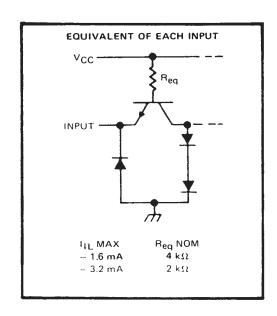


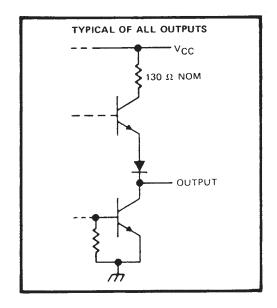
[†]These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

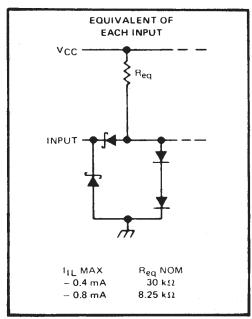
'73

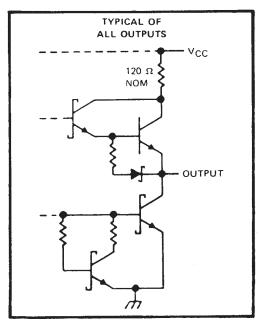
'LS73

schematics of inputs and outputs

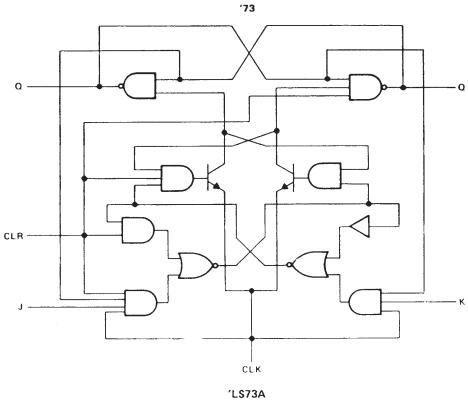


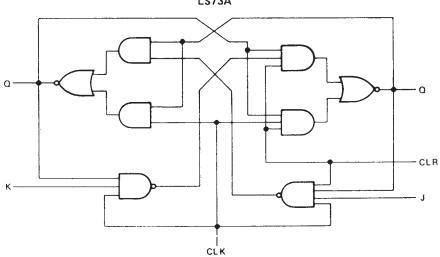






logic diagrams (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

| Supply voltage, VCC (See Note 1) | 7 V |
|---------------------------------------|--------------------|
| Input voltage: '73 | 5.5 V |
| LS73A | 7 V |
| Operating free-air temperature range: | SN54' |
| opolating the an earliest tanget | SN74' 0° C to 70°C |
| | -65°C to 150°C |

NOTE 1: Voltage values are with respect to network ground terminal.



SN5473, SN54LS73A, SN7473, SN74LS73A **DUAL J-K FLIP-FLOPS WITH CLEAR**

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recommended operating conditions

| | | | | SN547 | 3 | | SN747 | 3 | UNIT |
|-----------------|---------------------------------|----------|------|-------|------|------|-------|-------|------|
| | | | MIN | NOM | MAX | MIN | NOM | MAX | UNII |
| Vcc | Supply voltage | | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | ٧ |
| VIH | High-level input voltage | | 2 | | | 2 | | | ٧ |
| VIL | Low-level input voltage | | | | 0.8 | | | 0.8 | ٧ |
| ЮН | High-level output current | | | | -0.4 | | | - 0.4 | mA |
| loL | Low-level output current | | | | 16 | | | 16 | mA |
| | | CLK high | 20 | | | 20 | | | |
| tw | Pulse duration | CLK low | 47 | | | 47 | | | ns |
| | | CLR low | 25 | | | 25 | | | _ |
| t _{su} | Input setup time before CLK t | | 0 | | | 0 | | | ns |
| th | Input hold time data after CLK↓ | | 0 | | | 0 | | | ns |
| TA | Operating free-air temperature | | - 55 | | 125 | 0 | | 70 | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| | | | | unt. | | SN5473 | | | SN7473 | | |
|------|---------|---|--------------------------|--------------------------|------|--------|----------|----------|--------|----------|------|
| PA | RAMETER | 11 | EST CONDITION | 181 | MIN | TYP# | MAX | MIN | TYP‡ | MAX | UNIT |
| VIK | | V _{CC} = MIN, | I _I = - 12 mA | | | | - 1.5 | | | - 1.5 | V |
| Vон | | V _{CC} = MIN, I _{OH} = - 0.4 mA | V _{IH} = 2 V, | V _{IL} = 0.8 V, | 2.4 | 3.4 | | 2.4 | 3.4 | | V |
| VOL | | V _{CC} = MIN, I _{OL} = 16 mA | V _{IH} = 2 V, | V _{IL} = 0.8 V, | | 0.2 | 0.4 | | 0.2 | 0.4 | v |
| 11 | | V _{CC} = MAX, | V _I = 5.5 V | | | | 1 | | | 1 | mA |
| ЧН | J or K | V _{CC} = MAX, | V ₁ = 2.4 V | | | | 40 80 | | | 40 80 | μА |
| | J or K | | | | | | - 1.6 | | | - 1.6 | |
| ItL | CLR | V _{CC} = MAX, | V ₁ = 0.4 V | | | | - 3,2 | | | - 3.2 | mA |
| . – | CLK | | · | | | | - 3.2 | | | - 3.2 |] |
| los§ | | V _{CC} = MAX | | | - 20 | | - 57 | - 18 | | - 57 | mA |
| Icc1 | | V _{CC} = MAX, | See Note 2 | | | 10 | 20 | <u> </u> | 10 | 20 | mA |

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: With all outputs open, ICC is measured with the Q and \overline{Q} outputs high in turn. At the time of measurement, the clock input

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

| PARAMETER# | FROM (INPUT) | TO (OUTPUT) | TEST CONDITIONS | S MIN | TYP | MAX | UNIT |
|------------------|-----------------|----------------|----------------------------|---------|-----|-----|------|
| f _{max} | | | | 15 | 20 | | MHz |
| ^t PLH | CLR | ₫. | | | 16 | 25 | ns |
| ^t PHL | CLN | Q | $R_L = 400 \Omega$, C_L | = 15 pF | 25 | 40 | กร |
| ^t PLH | CLK | Q or Q | | | 16 | 25 | ns |
| ^t PHL | CLK | u or u | | | 25 | 40 | ns |

[#]fmax = maximum clock frequency: tpLH = propagation delay time, low-to-high-level output; tpHL = propagation delay time, high-tolow-level output.

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $^{^{\}ddagger}$ All typical values are at VCC = 5 V, TA = 25 °C.

[§] Not more than one output should be shorted at a time.

Average per flip-flop.

recommended operating conditions

| | | | SI | N54LS7 | 3A | Si | 174LS7 | 3A | |
|-----------------|--------------------------------|------------------|------|--------|-------|------|--------|-------|------|
| | | | MIN | NOM | MAX | MIN | NOM | MAX | UNIT |
| Vcc | Supply voltage | | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| ViH | High-level input voltage | | 2 | | | 2 | | | ٧ |
| VIL | Low-level input voltage | | | | 0.7 | | | 0.8 | V |
| Іон | High-level output current | | | | - 0.4 | | | - 0.4 | mA |
| lOL | Low-level output current | | | | 4 | | | 8 | mA |
| fclock | Clock frequency | | 0 | | 30 | 0 | | 30 | MHz |
| | Pulse duration | CLK high | 20 | | | 20 | | | |
| t _W | ruise duration | CLR low | 25 | | | 20 | - | | กร |
| | See and since before OLKI | data high or low | 20 | | | 20 | | | |
| t _{su} | Set up time-before CLK+ | CLR inactive | 20 | | | 20 | | | ns |
| th | th Hold time-data after CLK I | | | | | 0 | | | ns |
| TA | Operating free-air temperature | | - 55 | | 125 | 0 | | 70 | °c |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| | RAMETER | | ST CONDITION | et | SI | N54LS73 | 3A | SI | N74LS7: | 3A | UNIT |
|----------------|------------|--|------------------------|------------------------|------|---------|--------------|------|---------|-------|------|
| PA | ARAMETER | | 251 COMPITION | <u> </u> | MIN | TYP# | MAX | MIN | TYP# | MAX | UNIT |
| VIK | | V _{CC} = MIN, | $t_1 = -18 \text{ mA}$ | | | | - 1.5 | | | - 1.5 | V |
| Voн | | V _{CC} = MIN, I _{OH} = - 0.4 mA | V _{IH} = 2 V, | V _{IL} = MAX, | 2.5 | 3.4 | | 2.7 | 3.4 | | ٧ |
| \/ - · | | V _{CC} = MIN, I _{OL} = 4 mA | V _{IL} = MAX, | V _{IH} = 2 V, | | 0.25 | 0.4 | | 0.25 | 0.4 | V |
| VOL | | V _{CC} = MIN, I _{OL} = 8 mA | V _{IL} = MAX, | V _{IH} = 2 V, | | | | | 0.35 | 0.5 | , v |
| | J or K | | | | | | 0.1 | | | 0.1 | |
| l _l | CLR | V _{CC} = MAX, | V! = 7 V | | | | 0.3 | | | 0.3 | mA |
| | CLK | | | | | | 0.4 | | | 0.4 | |
| | J or K | - | | | | | 20 | | | 20 | |
| чн | CLR | V _{CC} = MAX, | V ₁ = 2.7 V | | | | 60 | | | 60_ | μА |
| | CLK | | | | | | 80 | | | 80 | |
| | J or K | V | V = 0.4.V | | | | 0.4 | | | - 0,4 | mA |
| IL | CLR or CLK | V _{CC} = MAX, | V = 0.4 V | | | | - 0.8 | | | - 0.8 | IIIA |
| los\$ | | V _{CC} = MAX, | See Note 4 | | - 20 | | – 100 | - 20 | | - 100 | mA |
| ICC (T | otai) | V _{CC} = MAX, | See Note 2 | | | 4 | 6 | | 4 | 6 | mA |

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------|-----------------|--------------------------|---|-----|-----|-----|------|
| f _{max} | | | | 30 | 45 | | MHz |
| ^t PLH | CLR or CLK | Q or $\overline{\Omega}$ | $R_{\perp} = 2 k\Omega$, $C_{\perp} = 15 pF$ | | 15 | 20 | ns |
| ^t PHL | CER OF CER | Q or Q | | | 15 | 20 | ns |

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V_O = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.



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PACKAGING INFORMATION

| Orderable Device | Status | Package Type | Package Drawing | Pins | Package Qty | Eco Plan | Lead finish/ Ball material | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|--------|--------------|--------------------|------|----------------|---------------------|-------------------------------|--------------------|--------------|------------------------------------|---------|
| 5962-9675101QCA | ACTIVE | CDIP | J | 14 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9675101QC A SNJ54LS73AJ | Samples |
| 5962-9675101QDA | ACTIVE | CFP | W | 14 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9675101QD A SNJ54LS73AW | Samples |
| 5962-9675101QDA | ACTIVE | CFP | W | 14 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9675101QD A SNJ54LS73AW | Samples |
| SN54LS73AJ | ACTIVE | CDIP | J | 14 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | SN54LS73AJ | Samples |
| SN54LS73AJ | ACTIVE | CDIP | J | 14 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | SN54LS73AJ | Samples |
| SN74LS73AD | ACTIVE | SOIC | D | 14 | 50 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS73A | Samples |
| SN74LS73AD | ACTIVE | SOIC | D | 14 | 50 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS73A | Samples |
| SN74LS73ADR | ACTIVE | SOIC | D | 14 | 2500 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS73A | Samples |
| SN74LS73ADR | ACTIVE | SOIC | D | 14 | 2500 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS73A | Samples |
| SN74LS73AN | ACTIVE | PDIP | N | 14 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | 0 to 70 | SN74LS73AN | Samples |
| SN74LS73AN | ACTIVE | PDIP | N | 14 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | 0 to 70 | SN74LS73AN | Samples |
| SN74LS73ANE4 | ACTIVE | PDIP | N | 14 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | 0 to 70 | SN74LS73AN | Samples |
| SN74LS73ANE4 | ACTIVE | PDIP | N | 14 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | 0 to 70 | SN74LS73AN | Samples |
| SNJ54LS73AJ | ACTIVE | CDIP | J | 14 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9675101QC A SNJ54LS73AJ | Samples |
| SNJ54LS73AJ | ACTIVE | CDIP | J | 14 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9675101QC A SNJ54LS73AJ | Samples |
| SNJ54LS73AW | ACTIVE | CFP | W | 14 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9675101QD A | Samples |



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| Orderable Device | Status | Package Type | Package Drawing | Pins | Package Qty | Eco Plan | Lead finish/ Ball material | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|--------|--------------|--------------------|------|----------------|---------------------|-------------------------------|--------------------|--------------|------------------------------------|---------|
| | | | | | | | | | | SNJ54LS73AW | |
| SNJ54LS73AW | ACTIVE | CFP | W | 14 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9675101QD A SNJ54LS73AW | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS73A, SN74LS73A:

PACKAGE OPTION ADDENDUM

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• Military : SN54LS73A

NOTE: Qualified Version Definitions:

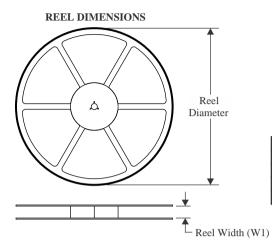
• Catalog - TI's standard catalog product

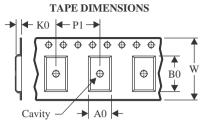
• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





| A0 | Dimension designed to accommodate the component width |
|----|---|
| В0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

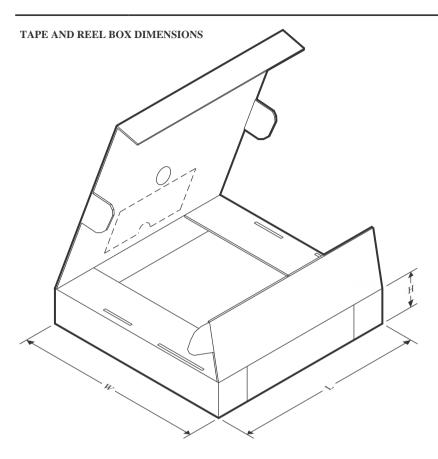


*All dimensions are nominal

| | Device | Package Type | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|-------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| L | SN74LS73ADR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74LS73ADR | SOIC | D | 14 | 2500 | 356.0 | 356.0 | 35.0 |

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (µm) | B (mm) |
|-----------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| 5962-9675101QDA | W | CFP | 14 | 1 | 506.98 | 26.16 | 6220 | NA |
| SN74LS73AD | D | SOIC | 14 | 50 | 506.6 | 8 | 3940 | 4.32 |
| SN74LS73AN | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74LS73AN | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74LS73ANE4 | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74LS73ANE4 | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SNJ54LS73AW | W | CFP | 14 | 1 | 506.98 | 26.16 | 6220 | NA |

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a certain is using glass int.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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